
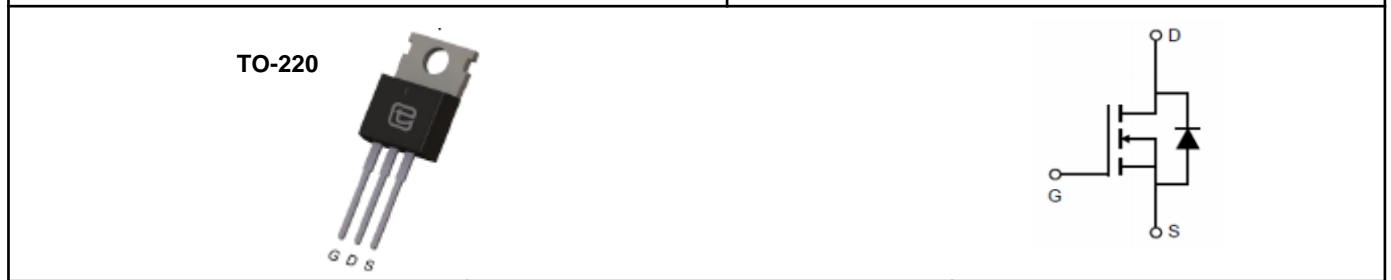




# 30V N-Channel Trench MOSFET(Preliminary)

<p><b>Features</b></p> <ul style="list-style-type: none"> <li>● Trench Power Technology</li> <li>● Low <math>R_{DS(ON)}</math></li> <li>● Low Gate Charge</li> <li>● Optimized for Fast-switching Applications</li> </ul> <p><b>Applications</b></p> <ul style="list-style-type: none"> <li>● Synchronous Rectification in DC/DC and AC/DC Converters</li> <li>● Isolated DC/DC Converters in Telecom and Industrial</li> </ul>	<p><b>Product Summary</b></p> <p>V<sub>DS</sub> 30V</p> <p><math>R_{DS(ON)}</math> (at V<sub>GS</sub>=10V) &lt; 5mΩ</p> <p><math>R_{DS(ON)}</math> (at V<sub>GS</sub>=4.5V) &lt; 7mΩ</p> <p>I<sub>D</sub> (at V<sub>GS</sub>=10V) 90A</p> <p>100% UIS Tested</p> 
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Device	Package	Marking
TTP90N03AT	TO-220	90N03AT

Absolute Maximum Ratings T <sub>C</sub> = 25°C, unless otherwise noted			
Parameter	Symbol	Value	Unit
Drain-Source Voltage (V <sub>GS</sub> = 0V)	V <sub>DSS</sub>	30	V
Continuous Drain Current <sup>B</sup>	I <sub>D</sub>	T <sub>C</sub> = 25°C	90
		T <sub>C</sub> = 100°C	63
Pulsed Drain Current <sup>A</sup>	I <sub>DM</sub>	270	A
Gate-Source Voltage	V <sub>GS</sub>	±20	V
Single Pulse Avalanche Energy L = 0.3mH <sup>A</sup>	E <sub>AS</sub>	72	mJ
Avalanche Current <sup>A</sup>	I <sub>AS</sub>	22	A
Power Dissipation <sup>C</sup>	P <sub>D</sub>	T <sub>C</sub> = 25°C	108
		T <sub>C</sub> = 100°C	82
Operating Junction and Storage Temperature Range	T <sub>J</sub> , T <sub>SGT</sub>	-55~+175	°C

Thermal Resistance			
Parameter	Symbol	Value	Unit
Thermal Resistance, Junction-to-Case	R <sub>thJC</sub>	1.45	°C/W
Thermal Resistance, Junction-to-Ambient	R <sub>thJA</sub>	100	



Specifications $T_J = 25^\circ\text{C}$ , unless otherwise noted						
Parameter	Symbol	Test Conditions	Value			Unit
			Min.	Typ.	Max.	
<b>Static</b>						
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS} = 0V, I_D = 250\mu\text{A}$	30	--	--	V
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS} = 30V, V_{GS} = 0V, T_J = 25^\circ\text{C}$	--	--	1	$\mu\text{A}$
		$V_{DS} = 30V, V_{GS} = 0V, T_J = 100^\circ\text{C}$	--	--	25	
Gate-Source Leakage	$I_{GSS}$	$V_{GS} = \pm 20V$	--	--	$\pm 100$	nA
Gate-Source Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 250\mu\text{A}$	1.0	1.7	2.4	V
Static Drain-Source On-Resistance	$R_{DS(on)}$	$V_{GS} = 10V, I_D = 30A$	--	3.6	5.0	$\text{m}\Omega$
		$V_{GS} = 4.5V, I_D = 30A$	--	5	7.0	$\text{m}\Omega$
Forward Transconductance	$g_{fs}$	$V_{DS} = 10V, I_D = 20A$	17.3	--	--	S
<b>Dynamic</b>						
Input Capacitance	$C_{iss}$	$V_{GS} = 0V,$ $V_{DS} = 15V,$ $f = 1.0\text{MHz}$	--	1608	--	$\text{pF}$
Output Capacitance	$C_{oss}$		--	513	--	
Reverse Transfer Capacitance	$C_{rss}$		--	297	--	
Total Gate Charge	$Q_g$	$V_{DD} = 15V, I_D = 50A,$ $V_{GS} = 10V$	--	62	--	nC
Gate-Source Charge	$Q_{gs}$		--	7	--	
Gate-Drain Charge	$Q_{gd}$		--	13	--	
Turn-on Delay Time	$t_{d(on)}$	$V_{DD} = 15V, I_D = 50A,$ $R_G = 3\Omega$	--	13	--	ns
Turn-on Rise Time	$t_r$		--	17	--	
Turn-off Delay Time	$t_{d(off)}$		--	42	--	
Turn-off Fall Time	$t_f$		--	13	--	
<b>Drain-Source Body Diode Characteristics</b>						
Continuous Body Diode Current <sup>B</sup>	$I_S$	$T_C = 25^\circ\text{C}$	--	--	46	A
Pulsed Diode Forward Current <sup>A</sup>	$I_{SM}$		--	--	270	
Body Diode Voltage	$V_{SD}$	$T_J = 25^\circ\text{C}, I_{SD} = 30A, V_{GS} = 0V$	--	--	1.2	V
Reverse Recovery Time	$t_{rr}$	$I_F = 30A,$ $di_F/dt = 100A/\mu\text{s}$	--	40	--	ns
Reverse Recovery Charge	$Q_{rr}$		--	88	--	nC

**Notes**

1. Repetitive Rating: Pulse Width limited by maximum junction temperature
2.  $V_{DD} = 30V, R_G = 25\Omega$ , Starting  $T_J = 25^\circ\text{C}$
3. Pulse Test: Pulse Width  $\leq 300\mu\text{s}$ , Duty Cycle  $\leq 1\%$



Typical Characteristics  $T_J = 25^\circ\text{C}$ , unless otherwise noted

Figure 1. Output Characteristics

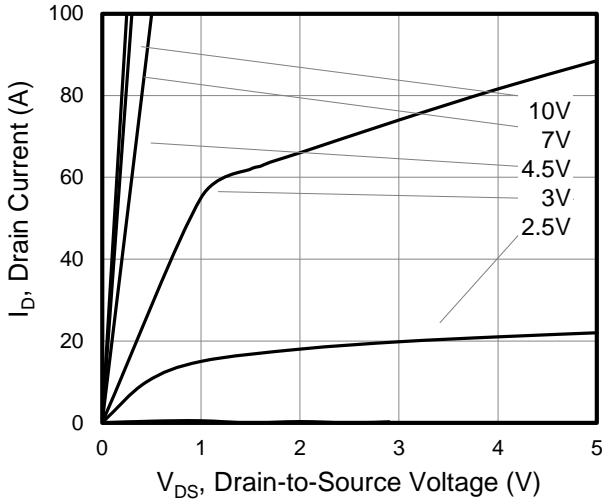


Figure 2. Transfer Characteristics

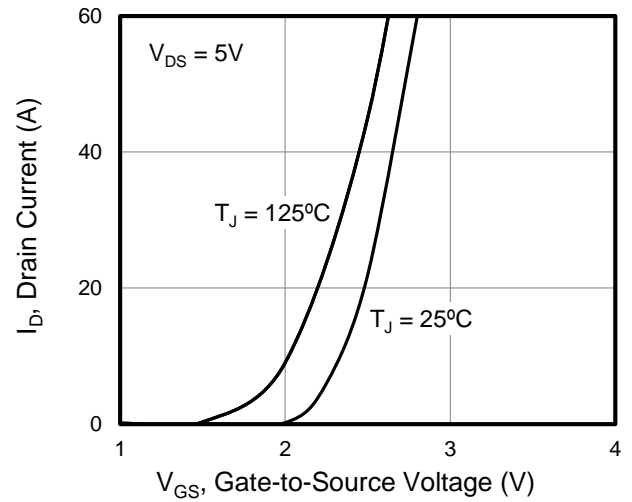


Figure 3. On-Resistance vs. Drain Current

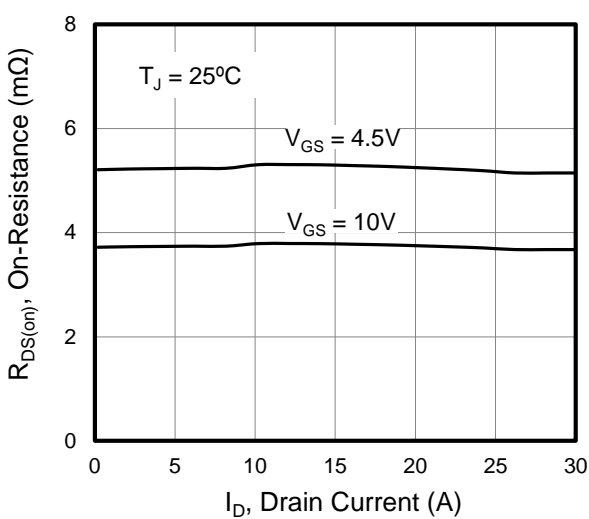


Figure 4. Capacitance

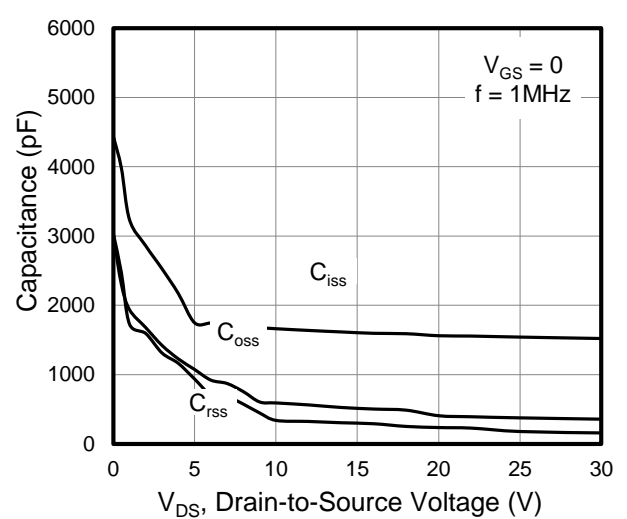


Figure 5. Gate Charge

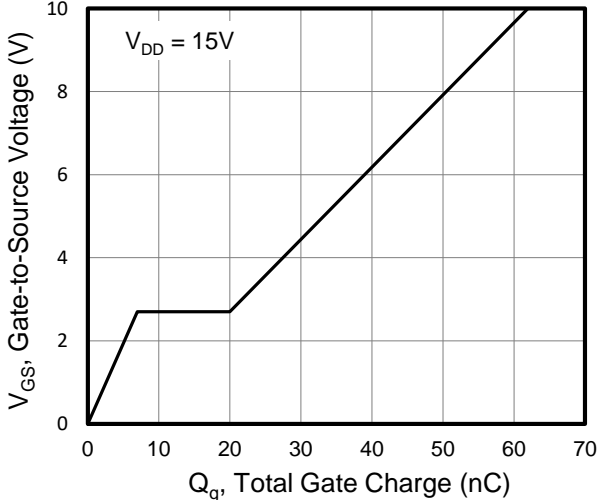
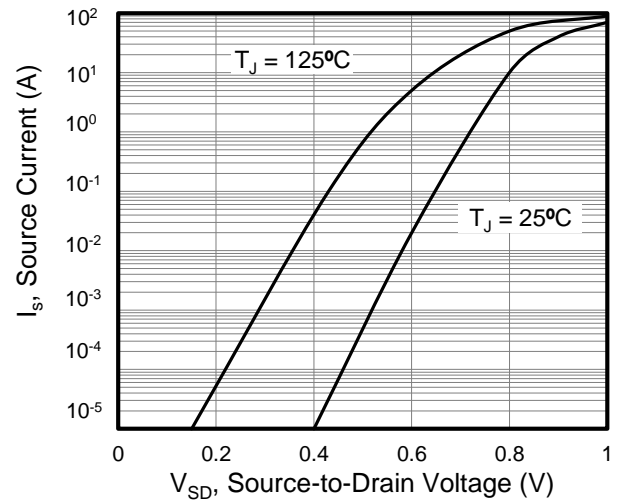


Figure 6. Body Diode Forward Voltage





Typical Characteristics  $T_J = 25^\circ\text{C}$ , unless otherwise noted

Figure 7. On-Resistance vs. Junction Temperature

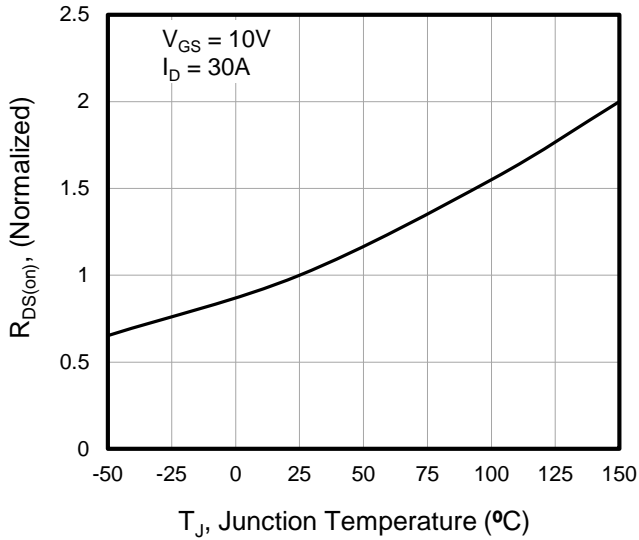


Figure 8. Threshold Voltage vs. Junction Temperature

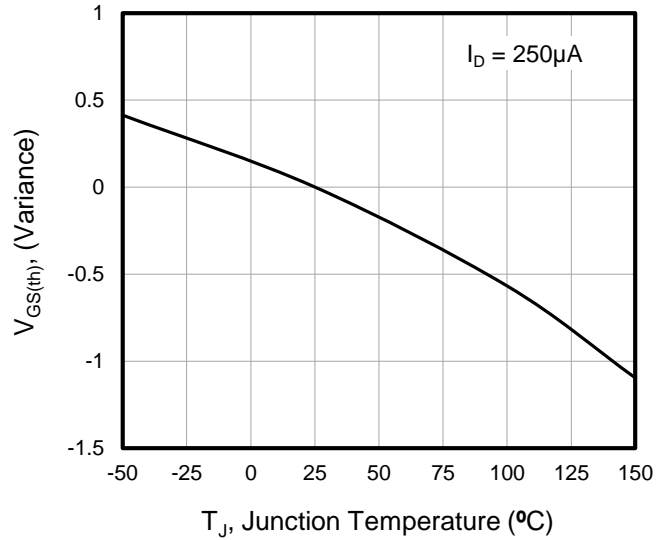


Figure 9. Transient Thermal Impedance

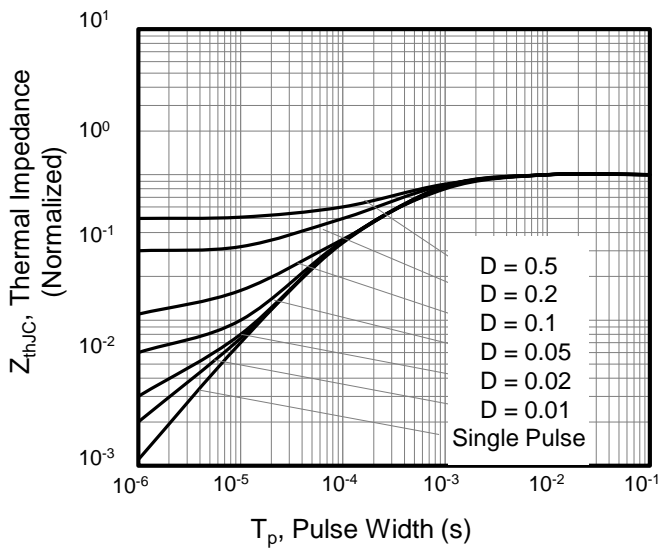


Figure 10. Safe operation area

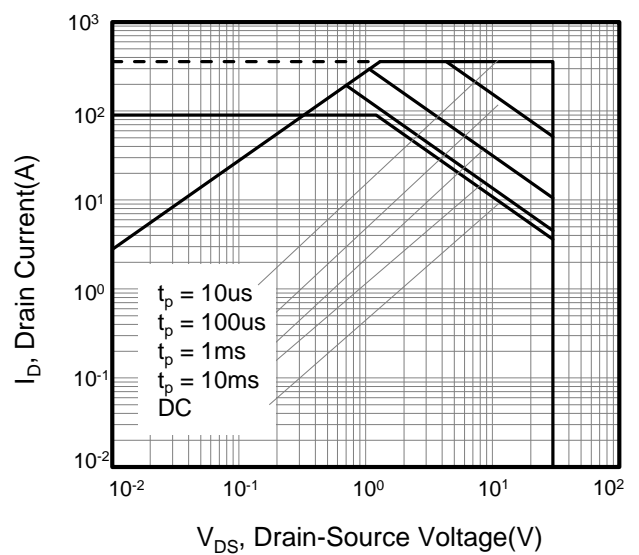




Figure A: Gate Charge Test Circuit and Waveform

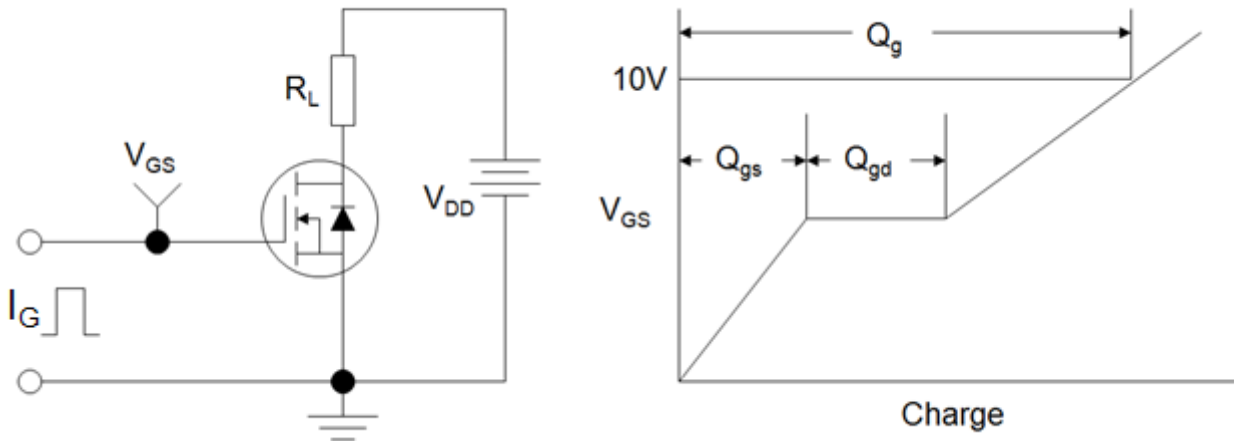


Figure B: Resistive Switching Test Circuit and Waveform

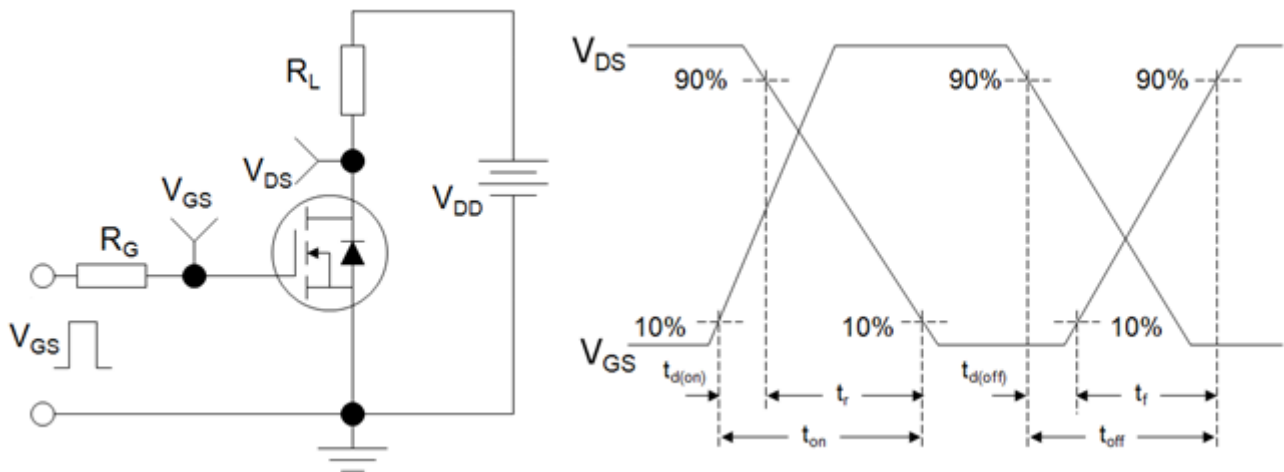
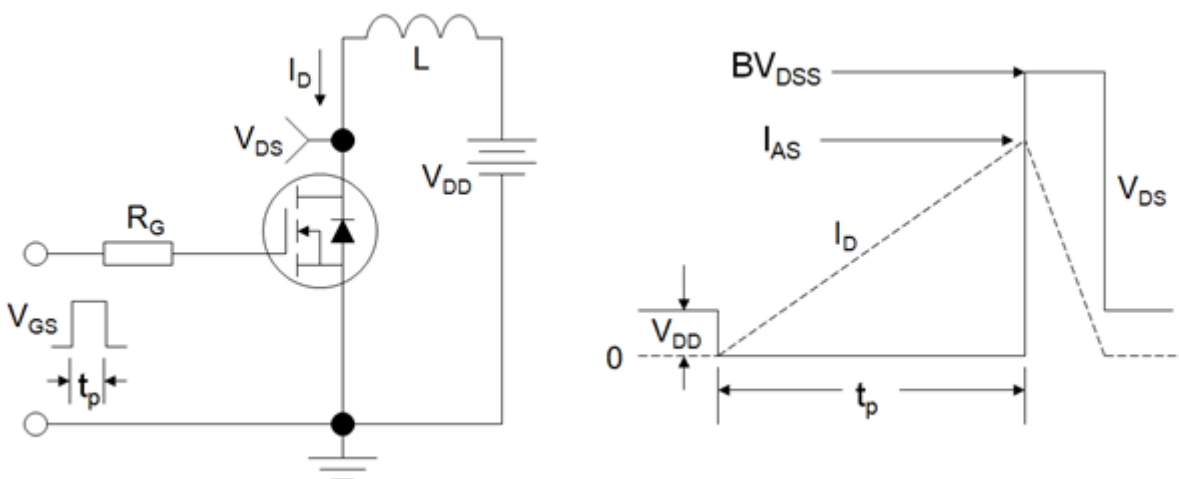
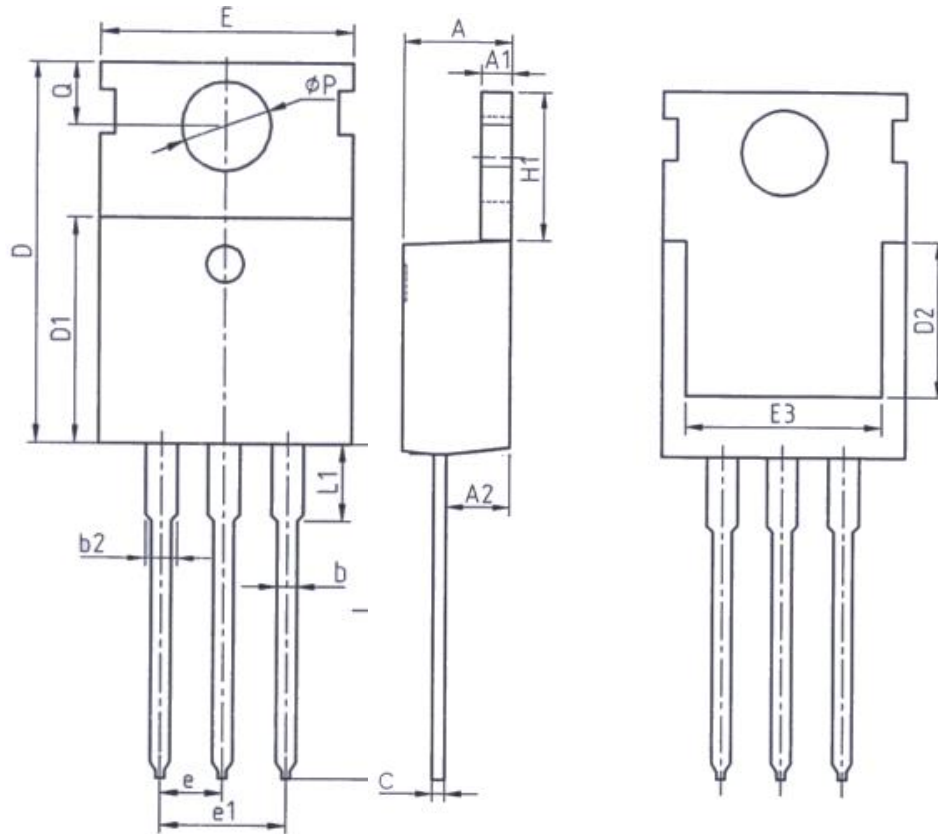


Figure C: Unclamped Inductive Switching Test Circuit and Waveform





## TO-220(H)



Unit: mm		
Symbol	Min.	Max.
A	4.37	4.77
A1	1.25	1.45
A2	2.20	2.60
b	0.70	0.95
b2	1.17	1.47
c	0.40	0.65
D	15.10	16.10
D1	8.80	9.40
D2	5.50	-

Unit: mm		
Symbol	Min.	Max.
E	9.70	10.30
E3	7.00	-
e	2.54BSC	
e1	5.08BSC	
H1	6.25	6.85
L	12.75	13.80
L1	-	3.40
P	3.40	3.80
Q	2.60	3.00



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